

Title (en)

METHOD OF SAWING CRYSTAL BARS AND PLURAL-BLADE SAW WITH ANNULAR MEMBERS FOR CARRYING OUT THIS METHOD

Publication

EP 0093406 B1 19860723 (DE)

Application

EP 83104148 A 19830428

Priority

DE 3216200 A 19820430

Abstract (en)

[origin: US4513544A] Crystalline rods or blocks can be sawed into thin wafers by sawing the rod or block into a plurality of wafers that are connected to each other. The wafers can be connected by introducing a connecting agent after each sawing step, into the resulting cutting gaps. The wafers are separated only after the whole rod has been sawed. The method makes possible the use of multiple-blade internal-hole saws, and preferably two-blade internal-hole saws.

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IPC 8 full level

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CPC (source: EP US)

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